

# Lonten N-channel 40V, 60A, 7.5mΩ Power MOSFET

## **Description**

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and with stand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

#### **Features**

- $\bullet$  40V,60A,R<sub>DS(ON).max</sub>=7.5m $\Omega$ @V<sub>GS</sub>=10V
- Improved dv/dt capability
- Fast switching
- ♦ 100% EAS Guaranteed
- ◆ Green device available

## **Applications**

- Motor Drives
- ◆ UPS
- DC-DC Converter

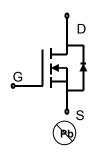
#### **Product Summary**

 $\begin{array}{ll} V_{DSS} & 40V \\ R_{DS(on).max} \textcircled{0} \ V_{GS} = 10V & 7.5 m\Omega \\ I_D & 60A \end{array}$ 

## **Pin Configuration**







N-Channel MOSFET

## **Absolute Maximum Ratings** T<sub>C</sub> = 25°C unless otherwise noted

Parameter	Symbol	Value	Unit	
Drain-Source Voltage	V <sub>DSS</sub>	40	V	
Continuous drain current ( Tc = 25°C )		60	A	
Continuous drain current ( Tc = 100°C )	- I <sub>D</sub>	38	A	
Pulsed drain current <sup>1)</sup>	Ідм	240	A	
Gate-Source voltage	V <sub>GSS</sub>	±20	V	
Avalanche energy <sup>2)</sup>	E <sub>AS</sub>	132	mJ	
Power Dissipation ( T <sub>C</sub> = 25°C )	P <sub>D</sub>	46	W	
Storage Temperature Range	T <sub>STG</sub>	-55 to +150	°C	
Operating Junction Temperature Range	TJ	-55 to +150	°C	

#### **Thermal Characteristics**

Parameter	Symbol	Value	Unit	
Thermal Resistance, Junction-to-Case	R <sub>в</sub> ус	2.7	°C/W	



**Package Marking and Ordering Information** 

Device	Device Package	Marking
LNN04R075	DFN5×6	LNN04R075

## **Electrical Characteristics** T<sub>J</sub> = 25°C unless otherwise noted

Parameter	Symbol	mbol Test Condition		Тур.	Max.	Unit	
Static characteristics				'	•		
Drain-source breakdown voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0 V, I <sub>D</sub> =250uA	40			V	
Gate threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250uA	1.0		2.0	V	
		V <sub>DS</sub> =40 V, V <sub>GS</sub> =0 V, T <sub>J</sub> = 25°C		1		μA	
Drain-source leakage current	I <sub>DSS</sub>	V <sub>DS</sub> =32 V, V <sub>GS</sub> =0 V, T <sub>J</sub> = 125°C			10	μA	
Gate leakage current, Forward	I <sub>GSSF</sub>	V <sub>GS</sub> =20 V, V <sub>DS</sub> =0 V			100	nA	
Gate leakage current, Reverse	I <sub>GSSR</sub>	V <sub>GS</sub> =-20 V, V <sub>DS</sub> =0 V			-100	nA	
Dunin anguna an atata masiatana	Б	V <sub>GS</sub> =10 V, I <sub>D</sub> =20 A		5.8	7.5	mΩ	
Drain-source on-state resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =4.5 V, I <sub>D</sub> =10 A		7.5	7.5 9.5		
Forward transconductance	<b>g</b> fs	g <sub>fs</sub> V <sub>DS</sub> =5 V , I <sub>D</sub> =20 A		63		S	
Dynamic characteristics							
Input capacitance	C <sub>iss</sub>	\/ - 20\/ \/ - 0\/		2370			
Output capacitance	Coss	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V},$ $V_{DS} = 1 \text{ MHz}$		316		pF	
Reverse transfer capacitance	Crss	- F = 1WIDZ		212			
Turn-on delay time	t <sub>d(on)</sub>			6.6			
Rise time	t <sub>r</sub>	$V_{DD} = 32V, V_{GS} = 10V, I_D = 20 A$		110.6		ns	
Turn-off delay time	t <sub>d(off)</sub>	VDD - 32V,VGS-10V, ID -20 A		285.4			
Fall time	t <sub>f</sub>			121.1			
Gate resistance	Rg	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, F=1MHz		1.7		Ω	
Gate charge characteristics							
Gate to source charge	Q <sub>gs</sub>			9.2			
Gate to drain charge	Q <sub>gd</sub>	V <sub>DS</sub> =32 V, I <sub>D</sub> =20A,		9.6		nC	
Gate charge total	Qg	- V <sub>GS</sub> = 10 V		51.2			
Drain-Source diode characteristi	cs and Maxi	mum Ratings		1		-	
Continuous Source Current	Is				60	Α	
Pulsed Source Current <sup>3)</sup>	I <sub>SM</sub>				240	Α	
Diode Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =20A, T <sub>J</sub> =25℃			1.2	V	
Reverse Recovery Time	t <sub>rr</sub>	1 00A 45/44 400A		22.4		ns	
Reverse Recovery Charge	Qrr	I <sub>S</sub> =20A,di/dt=100A/us, T <sub>J</sub> =25℃		10.5		nC	

#### Notes:

- 1: Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2:  $V_{DD}$ =20V,  $V_{GS}$ =10V, L=0.5mH, I<sub>AS</sub>=23A, R<sub>G</sub>=25 $\Omega$ , Starting T<sub>J</sub>=25 $^{\circ}$ C.
- 3: Pulse Test: Pulse Width  $\leq$ 300  $\mu$  s, Duty Cycle  $\leq$ 2%.

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#### **Electrical Characteristics Diagrams**

Figure 1. Typ. Output Characteristics

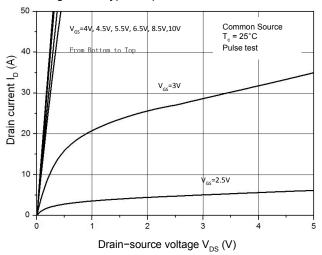


Figure 2. Transfer Characteristics

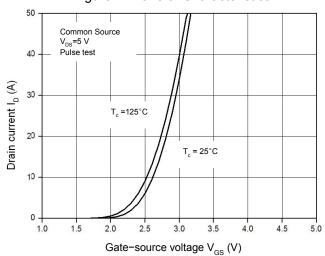


Figure 3. Capacitance Characteristics

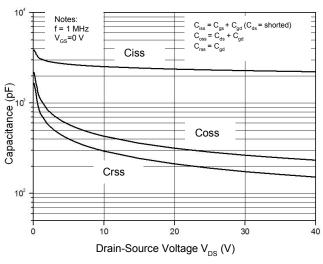


Figure 4. Gate Charge Waveform

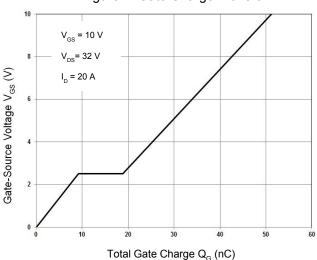


Figure 5. Body-Diode Characteristics

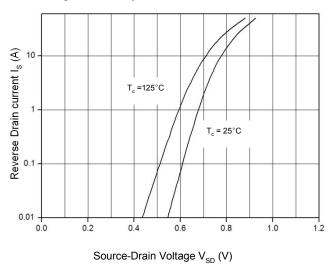


Figure 6. Rdson-Drain Current

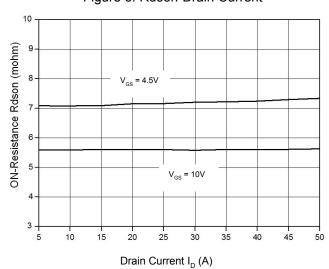




Figure 7. Rdson-Junction Temperature ( $^{\circ}$ C)

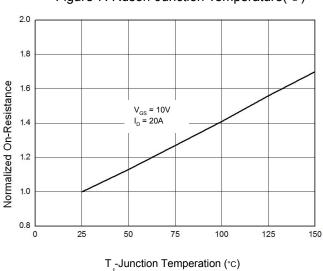


Figure 8. Maximum Safe Operating Area

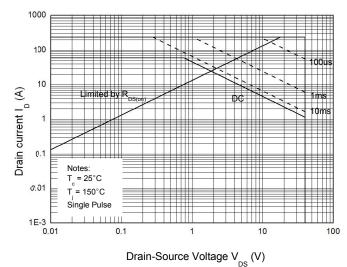
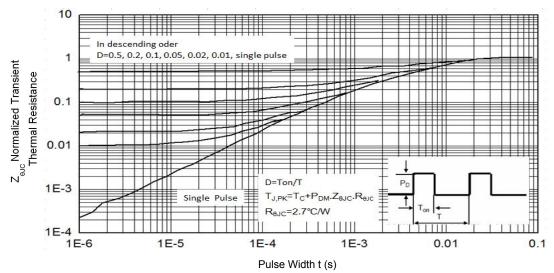


Figure 9. Normalized Maximum Transient Thermal Impedance (RthJC)

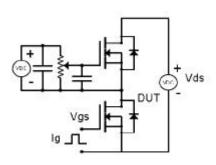


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## **Test Circuit & Waveform**

Figure 10. Gate Charge Test Circuit & Waveform



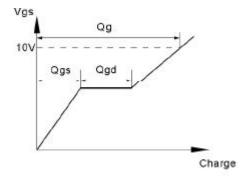
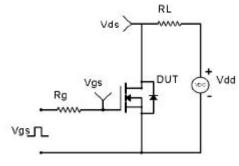


Figure 11. Resistive Switching Test Circuit & Waveforms



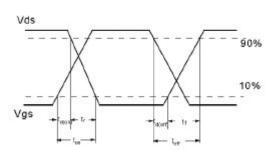
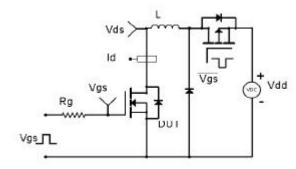


Figure 12. Unclamped Inductive Switching (UIS) Test Circuit & Waveform



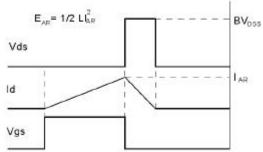
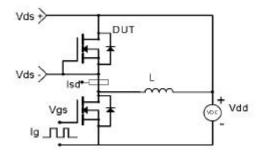
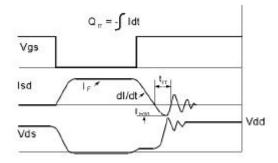


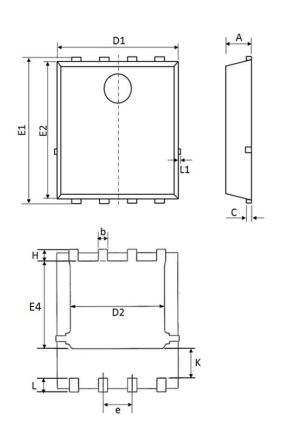
Figure 13. Diode Recovery Circuit & Waveform





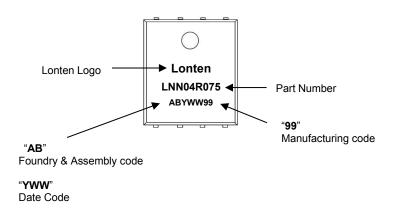


# **Mechanical Dimensions for DFN5×6**



COMMON DIMENSIONS						
SYMBOL	MILLIMETERS			INCHS		
	MIN	NOM	MAX	MIN	NOM	MAX
А	1	1.1	1.2	0.039	0.043	0.047
b	0.3	0.4	0.5	0.012	0.016	0.020
С	0.154	0.254	0.354	0.006	0.010	0.014
D1	5	5.2	5.4	0.197	0.205	0.213
D2	3.8	4.1	4.25	0.150	0.161	0.167
E1	5.95	6.15	6.35	0.234	0.242	0.250
E2	5.66	5.86	6.06	0.223	0.231	0.239
E4	3.52	3.72	3.92	0.139	0.146	0.154
е	1.27 BSC			0.050 BSC		
Н	0.4	0.5	0.6	0.016	0.020	0.024
L	0.5	0.6	0.7	0.020	0.024	0.028
L1	-	-	0.12	-	-	0.005
К	1.14	1.29	1.44	0.045	0.051	0.057

## **DFN5×6 Part Marking Information**





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